

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

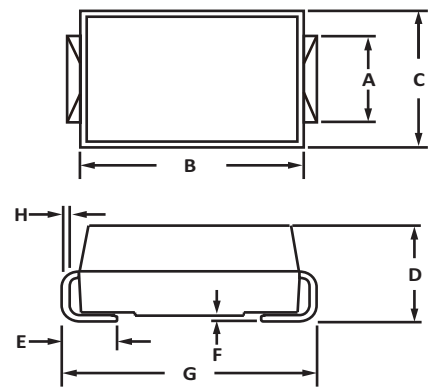


PLED

Product data sheet

SURGE RATINGS

PART NUMBER	VPP 10x700us (V)	IPP 5x310us (A)
P0080TA-MS	2KV	50



DO-214AC

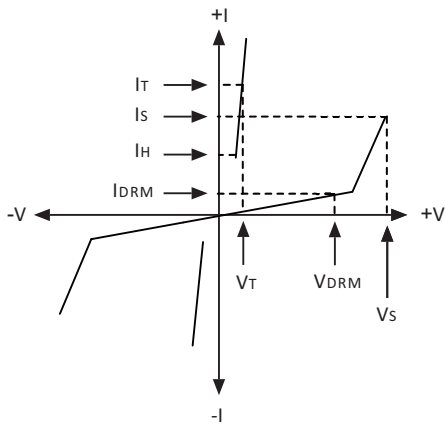
PART NUMBER AND ELECTRICAL PARAMETER @ T=25℃ RH = 45%- 75%

TYPE	VDRM(V)	IDRM(uA)	Vs (v)	Is(ma)	Vr (v)	It(a)	Ih(ma)	CJ
P0080TA-MS	6	5	25	800	4	2.2	40	25

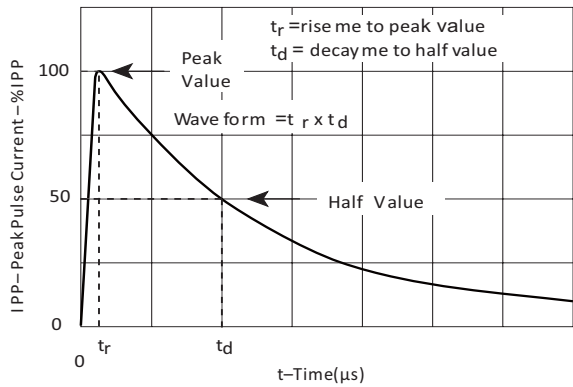
- ※ Vs is measured at 100KV/S
- ※ Off-state capacitance is measured in VDC=2V, VRMS=1V,F=1MHz
- ※ All measurements are made at an ambient temperature of 25 ℃

THERMAL CONSIDERATIONS

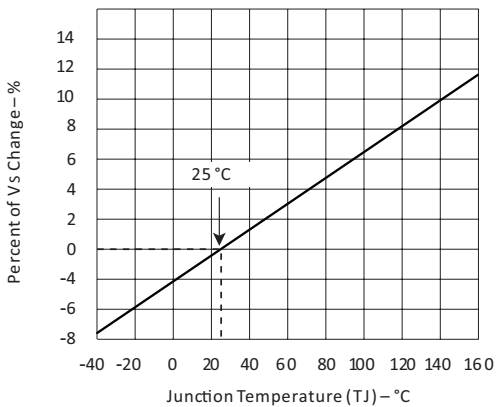
Symbol	Parameter	Value	Unit
TJ	Operating Junction Temperature	-55 to +125	℃
TS	Storage Temperature Range	-55 to +150	℃
RθJA	Junction to Ambient on printed circuit	120	℃/W



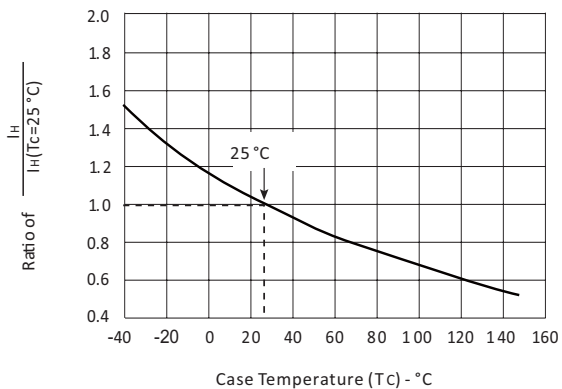
V-I Characteristics



$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature



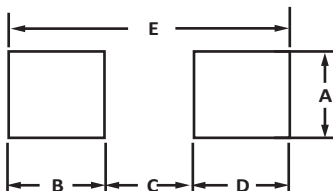
Normalized DC Holding Current vs. Case Temperature

SMA PACKAGE DIMENSIONS

The image shows a technical drawing of an SMA (Surface Mount Air) package. The top view shows a rectangular package with dimensions A (height of the central body), B (width of the central body), and C (total height including mounting tabs). The side view shows the package profile with dimensions D (total height), E (width of the mounting tabs), F (height of the mounting tabs), and G (total width including mounting tabs). The package has a central rectangular body and two mounting tabs on opposite sides.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.23	1.63	0.048	0.064
B	4.10	4.55	0.161	0.179
C	2.60	2.80	0.102	0.110
D	2.15	2.35	0.085	0.093
E	0.75	1.51	0.030	0.059
F	0.02	0.20	0.001	0.008
G	4.87	5.22	0.192	0.206
H	0.15	0.30	0.006	0.012
NOTES: 1.Dimensions are exclusive of mold flash and metal burrs				

RECOMMENDED PAD LAYOUT DIMENSION

	RECOMMENDED PAD LAYOUT DIMENSION				
	DIM	MILLIMETERS		INCHES	
		MIN	MAX	MIN	MAX
	A	1.63	-	0.064	-
	B	1.45	-	0.057	-
	C	-	2.28	-	0.090
	D	1.45	-	0.057	-
	E	5.28 REF		0.208 REF	

TYPE	PKG	QTY
P0080TA-MS	DO-214AC/SMA	7500

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